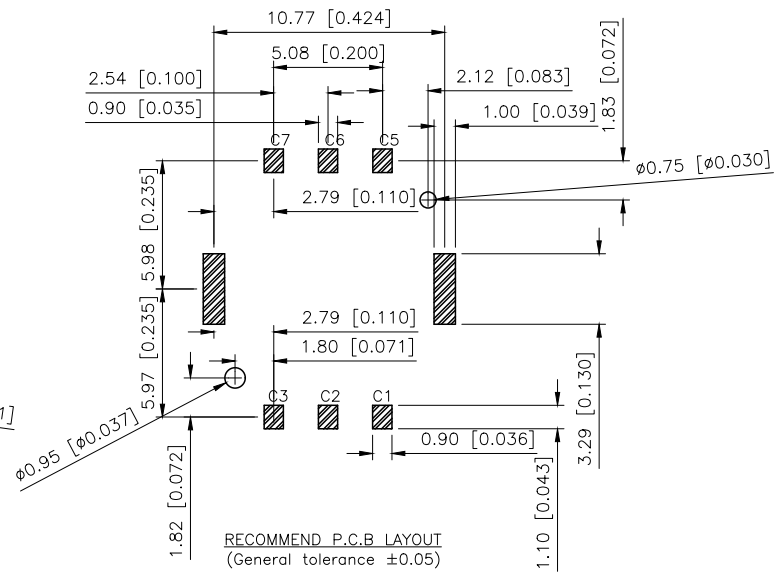
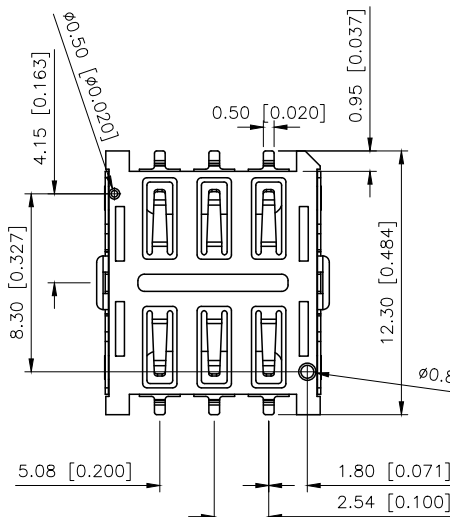
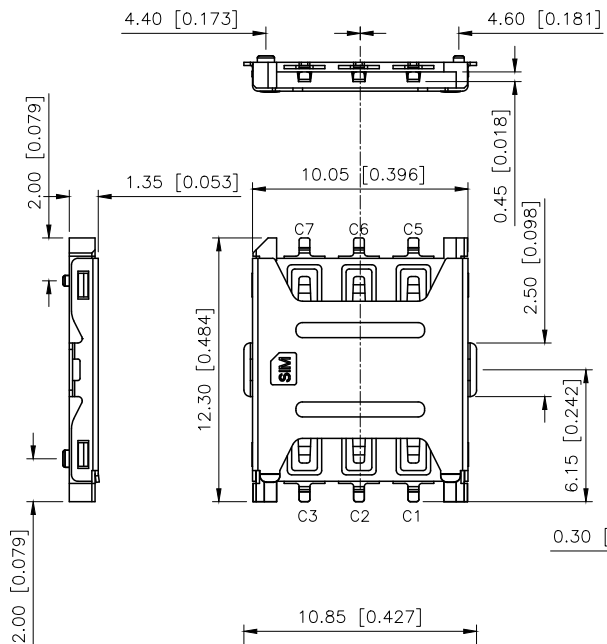


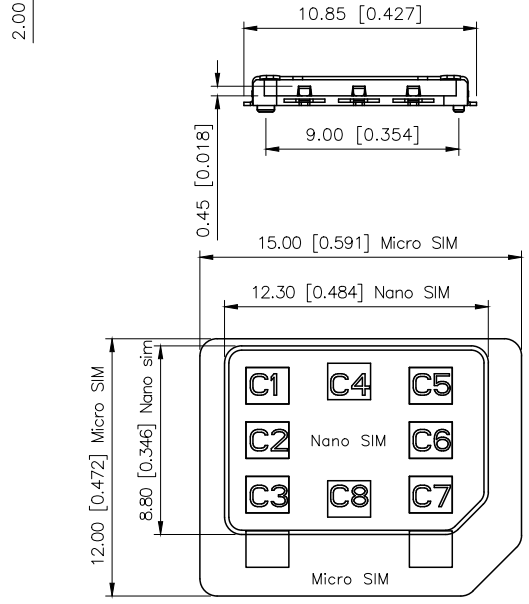
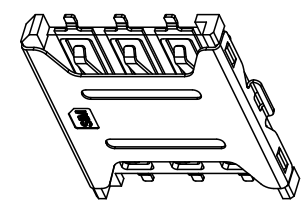
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.08	阿树



Specification

材料 MATERIAL:
绝缘材料 Insulator: High Temperature Thermoplastic, UL 94V-0.
触点 Contact:C5210
外壳 SHELL:SUS
电镀 PLATING:
触点 Contact:Plated 50u"Ni Overall Contact ALL Au 1U,
外壳 Shell:Plated 50u"Ni Overall,PAD Au 1U
电气 Electrical:
额定电流 Current Rating :0.5mA AC/DC max.
额定电压 Voltage Rating :125V AC/DC
环境温度 Ambient Temperature Range :-20°C+60°C
储存温度 Storage Temperature Range :-40°C+70°C
环境湿度 Ambient Humidity Range :95% R.H. Max.
接触电阻 Contact Resistance:100mΩ max.
绝缘电阻 Insulation Resistance:100MΩmin./500VDC
无通电寿命 Mating Cycles:10,000 Insertions
回流峰值温度 Reflow peak temp.:260°C ±5°C, 3~5 S
通电寿命 Mating Cycles:3,000 Insertions Min

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1151
APPROVED		SIZE: A4	DWG NO.: